

TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (L²-π-MOS V)

2SK4018

Chopper Regulator, DC/DC Converter and Motor Drive Applications

- 4 V gate drive
- Low drain-source ON-resistance : $R_{DS(ON)} = 0.28 \Omega$ (typ.)
- High forward transfer admittance : $|Y_{fs}| = 3.5 S$ (typ.)
- Low leakage current : $I_{DSS} = 100 \mu A$ (max) ($V_{DS} = 100 V$)
- Enhancement mode : $V_{th} = 0.8\sim 2.0 V$ ($V_{DS} = 10 V, I_D = 1 mA$)

Absolute Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating	Unit	
Drain-source voltage	V_{DSS}	100	V	
Drain-gate voltage ($R_{GS} = 20 k\Omega$)	V_{DGR}	100	V	
Gate-source voltage	V_{GSS}	± 20	V	
Drain current	DC (Note 1)	I_D	3	A
	Pulse (Note 1)	I_{DP}	12	A
Drain power dissipation ($T_c = 25^\circ C$)	P_D	20	W	
Single-pulse avalanche energy (Note 2)	E_{AS}	140	mJ	
Avalanche current	I_{AR}	3	A	
Repetitive avalanche energy (Note 3)	E_{AR}	2	mJ	
Channel temperature	T_{ch}	150	°C	
Storage temperature range	T_{stg}	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	6.25	°C / W
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	125	°C / W

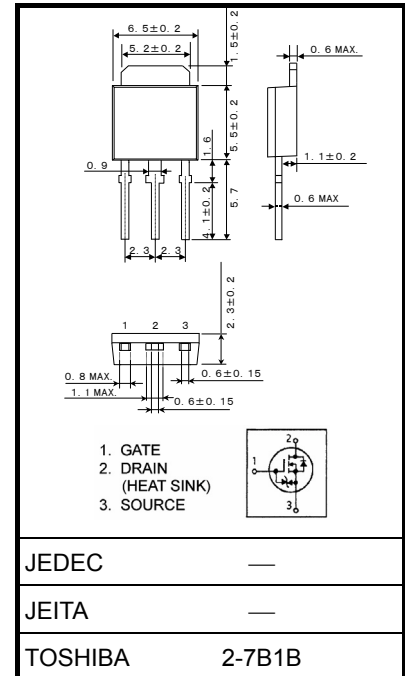
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: $V_{DD} = 50 V, T_{ch} = 25^\circ C$ (initial), $L = 25 mH, R_G = 25 \Omega, I_{AR} = 3 A$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

Unit: mm



Weight: 0.36 g (typ.)

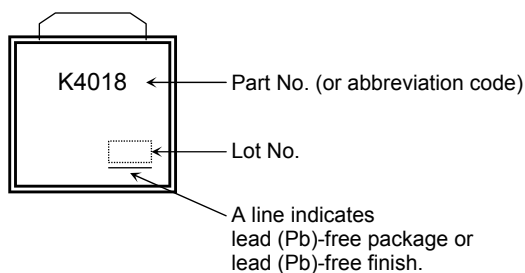
Electrical Characteristics (Ta = 25°C)

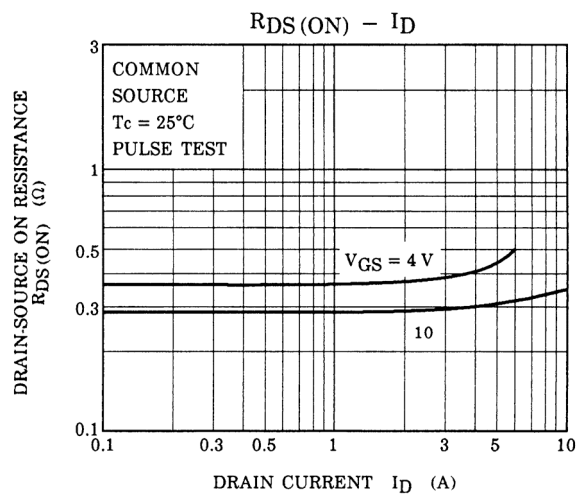
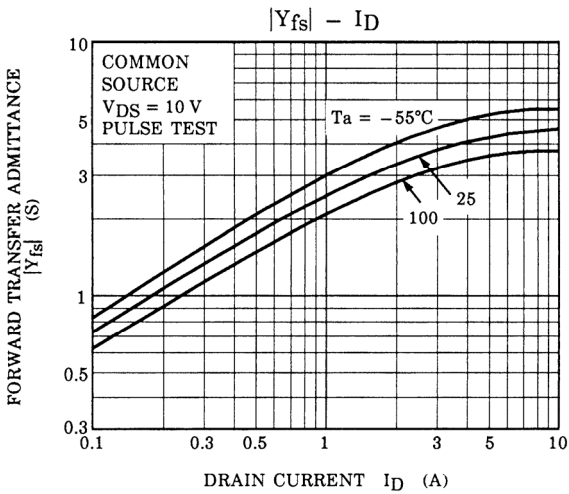
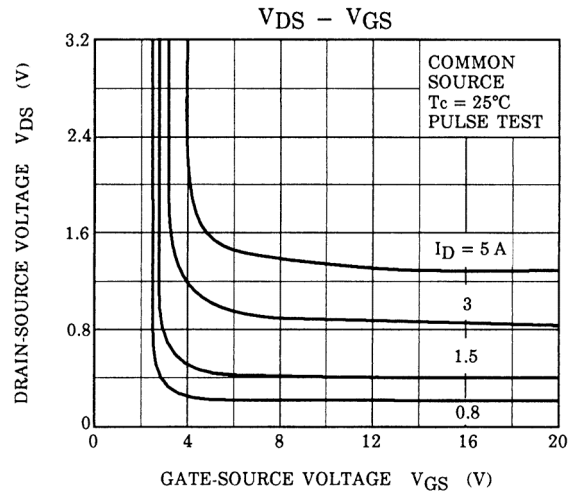
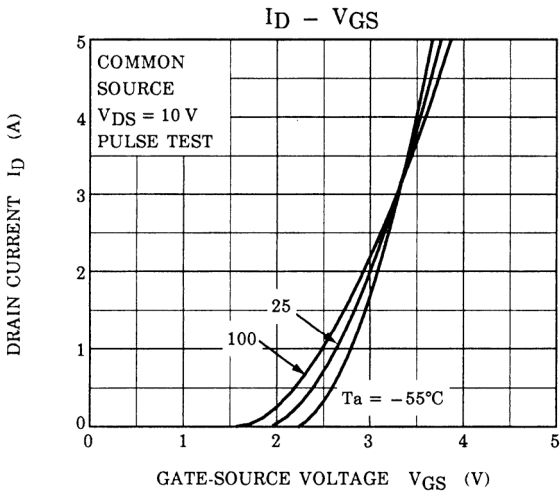
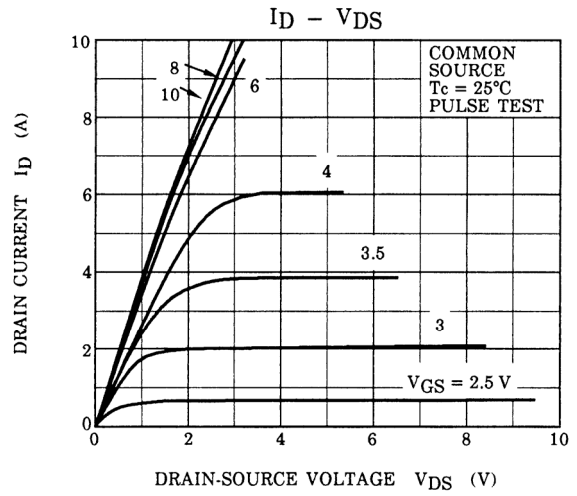
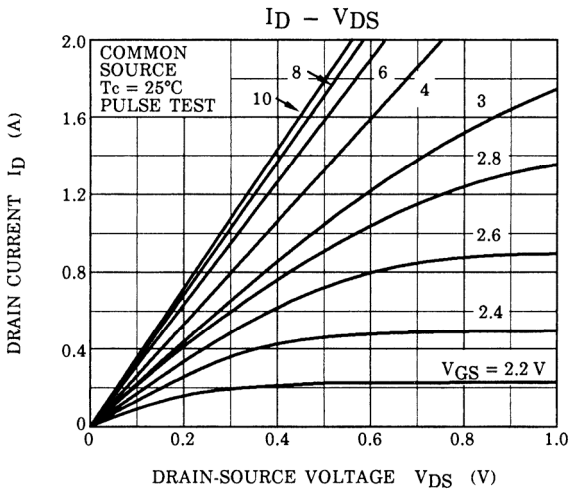
Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 16\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 10	μA
Drain cutoff current		I_{DSS}	$V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}$	—	—	100	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	100	—	—	V
Gate threshold voltage		V_{th}	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	0.8	—	2.0	V
Drain-source ON-resistance		$R_{DS(ON)}$	$V_{GS} = 4\text{ V}, I_D = 2\text{ A}$	—	0.36	0.45	Ω
			$V_{GS} = 10\text{ V}, I_D = 2\text{ A}$	—	0.28	0.35	
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 2\text{ A}$	1.5	3.5	—	S
Input capacitance		C_{iss}	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	280	—	pF
Reverse transfer capacitance		C_{rss}		—	50	—	
Output capacitance		C_{oss}		—	105	—	
Switching time	Rise time	t_r	<p>$I_D = 2\text{ A}$ $V_{GS} = 10\text{ V}$ $V_{DD} \approx 50\text{ V}$ $R_L = 25\ \Omega$ Duty $\leq 1\%$, $t_w = 10\ \mu\text{s}$</p>	—	20	—	ns
	Turn-on time	t_{on}		—	50	—	
	Fall time	t_f		—	40	—	
	Turn-off time	t_{off}		—	170	—	
Total gate charge (gate-source plus gate-drain)		Q_g	$V_{DD} \approx 80\text{ V}, V_{GS} = 10\text{ V}, I_D = 3\text{ A}$	—	13.5	—	nC
Gate-source charge		Q_{gs}		—	8.5	—	
Gate-drain ("Miller") charge		Q_{gd}		—	5	—	

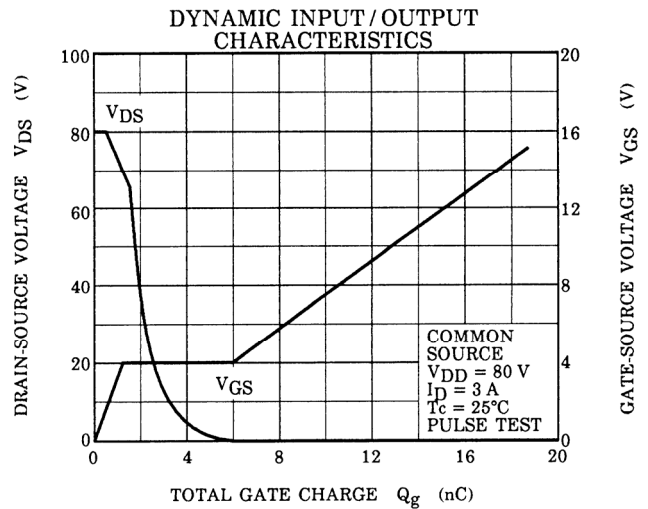
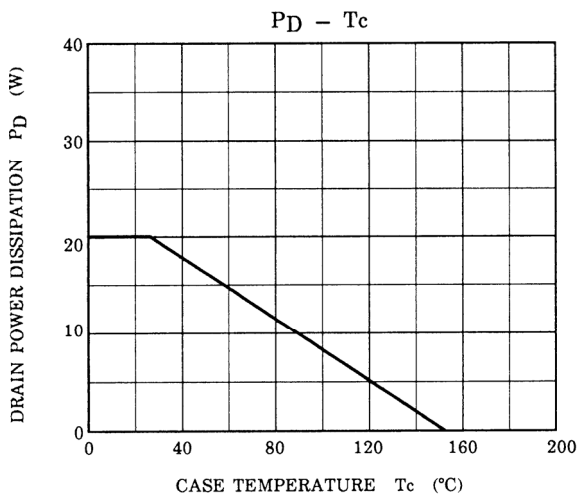
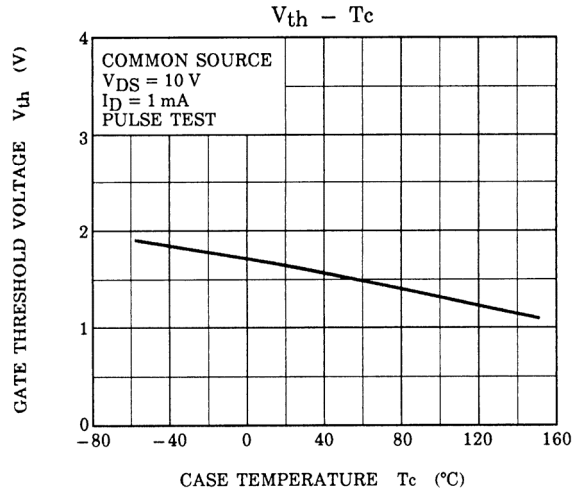
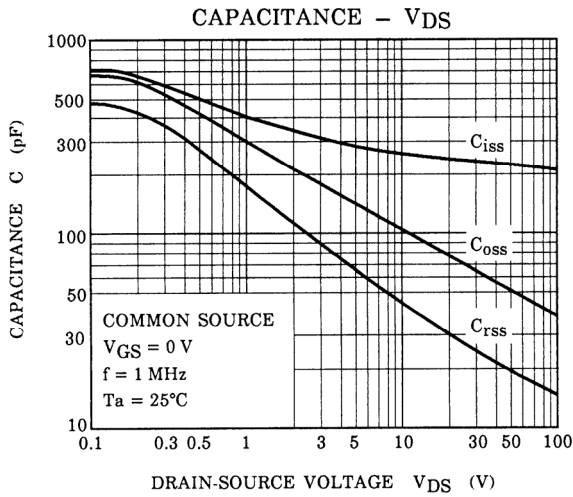
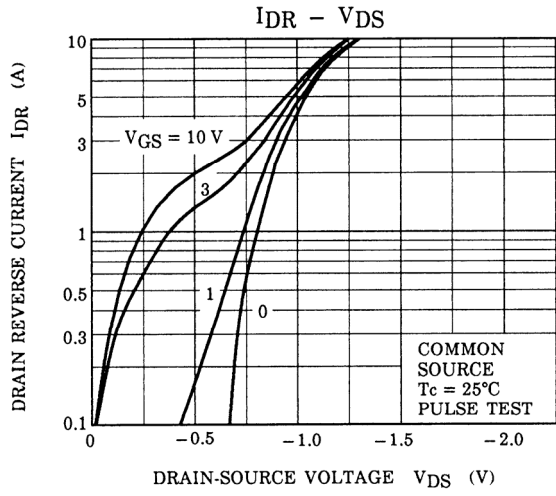
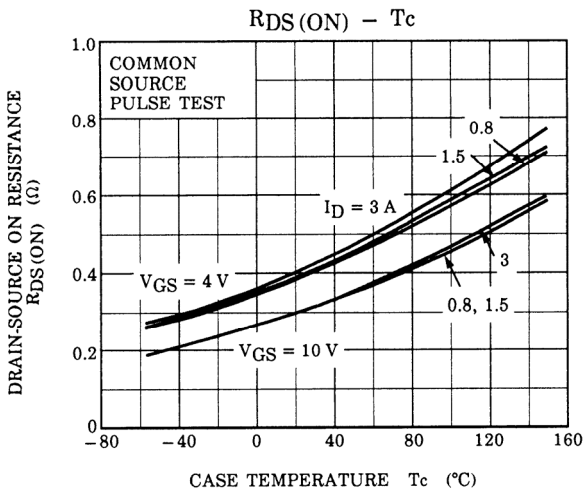
Source-Drain Ratings and Characteristics (Ta = 25°C)

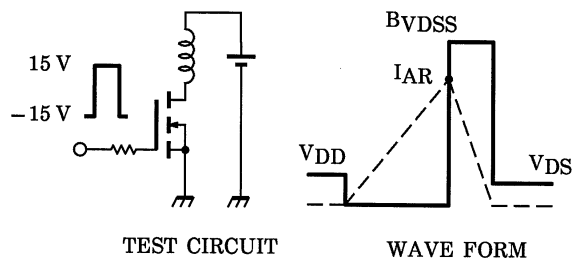
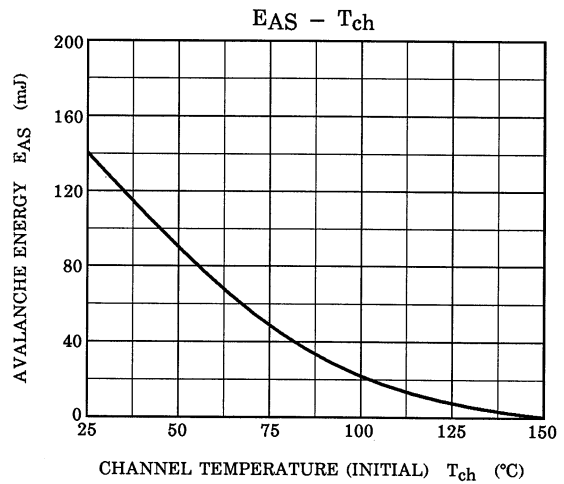
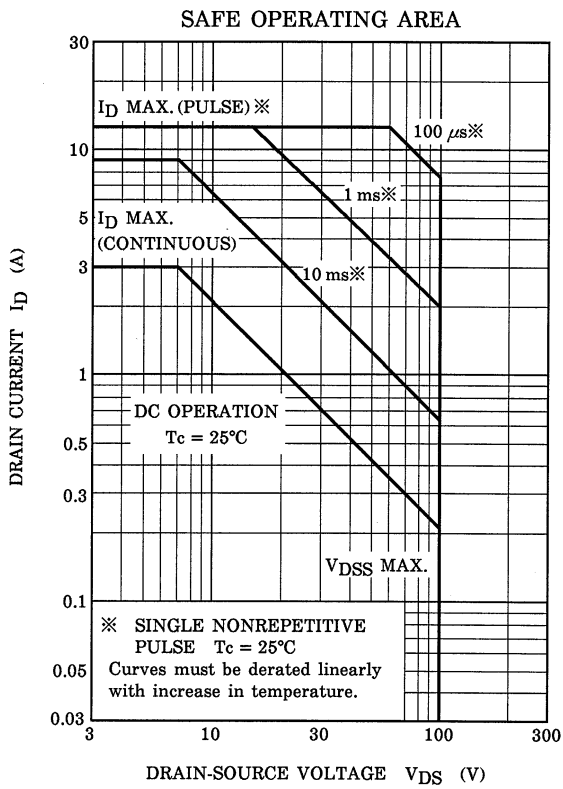
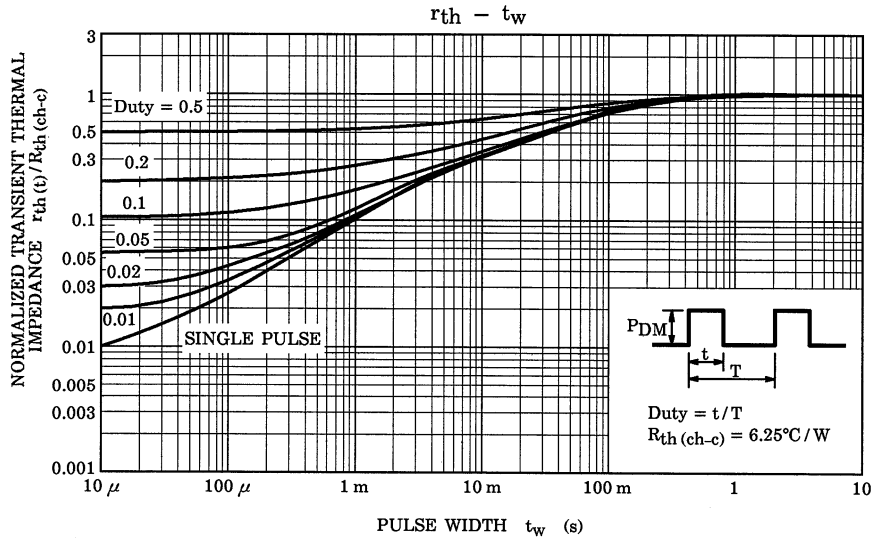
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	3	A
Pulse drain reverse current (Note 1)	I_{DRP}	—	—	—	12	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 3\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.5	V
Reverse recovery time	t_{rr}	$I_{DR} = 3\text{ A}, V_{GS} = 0\text{ V}, dI_{DR} / dt = 50\text{ A} / \mu\text{s}$	—	100	—	ns
Reverse recovery charge	Q_{rr}		—	0.2	—	μC

Marking









$R_G = 25 \Omega$
 $V_{DD} = 25 \text{ V}, L = 25 \text{ mH}$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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